

SERVICE BULLETIN

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Bulletin Part Number: 318882-B3

Product: L1 Compact Portable Line Array System

Subject: Low level audio distortion from line array when playing low frequency content.

Disposition: On all L1 Compact systems that were built between 1/7/13 (DOM 3007) and 6/15/16 (DOM 6167) that are sent in for repair due to the below symptom, remove the two SMD capacitors listed in step 2 of the following rework procedure.

- Any Service PCB's that are in stock must be reworked before being used in a repair.
- Any customer units that come in for this symptom only will be repaired free of charge.

Symptom: Low level distortion when playing low frequency content.

Reason: Amplifier IC manufacturer part characteristics change.

Solution: Perform the rework procedure below.

Rework Procedure:

CAUTION! Observe all ESD handling procedures to prevent damage to the PCB assembly during the rework process.

1. Using the disassembly procedures in the L1 Compact service manual, Remove the amplifier/SMPS PCB assembly from the power stand. Remove the aluminum heatsink plate from the bottom of the PCB assembly.
2. Locate SMD capacitors C56 and C64. They are located on the bottom side of the PCB assembly near the amplifier IC, U3. Using a soldering iron, carefully remove C56 and C64 and discard them. Refer to the photo at right for part locations.
3. Place fresh thermal grease onto the amplifier IC, U3, and re-assemble the heatsink to the amplifier/SMPS PCB assembly. Re-install the PCB assembly into the power stand.
4. Perform the test procedures located in the L1 Compact service manual before returning the system to the customer.

IMPORTANT NOTE: The Hi-Pot and Ground Bond tests **MUST** also be performed before returning the system to the customer. This is a Bose Safety requirement.

The Hi-Pot and Ground Bond test information is located on the L1 Compact Hi-Pot Test Information web page. There is a link to the L1 Compact Hi-Pot Training Power Point and a link to the Hi-Pot Testing Information Matrix sheet, which lists the connection points and test settings.

Note: Refer to the L1 Compact service manual, 318882-SM, located on the service web site located at <http://serviceops.bose.com> for disassembly and test procedures.

